

This document is the property of Amphenol Corporation and is delivered on the express condition that it is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



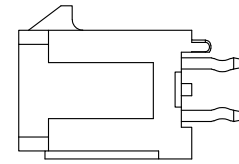
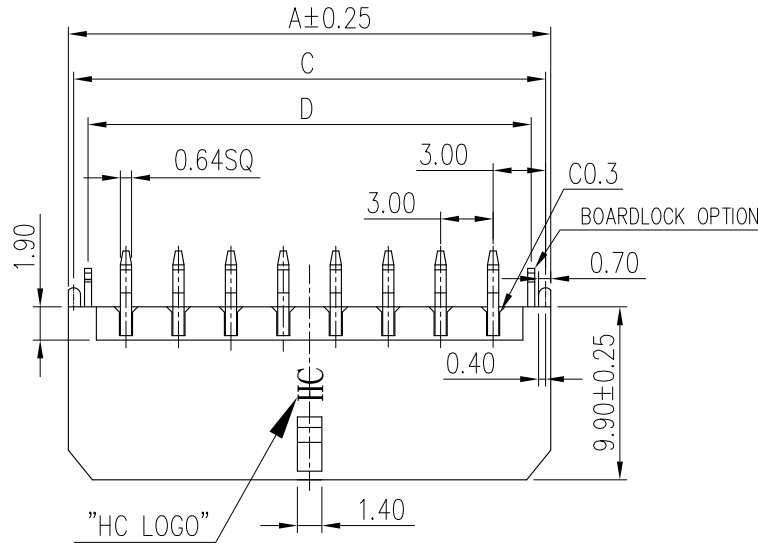
ORIGINAL



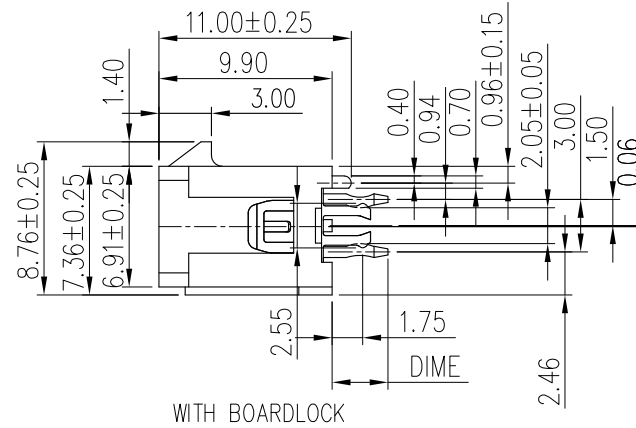
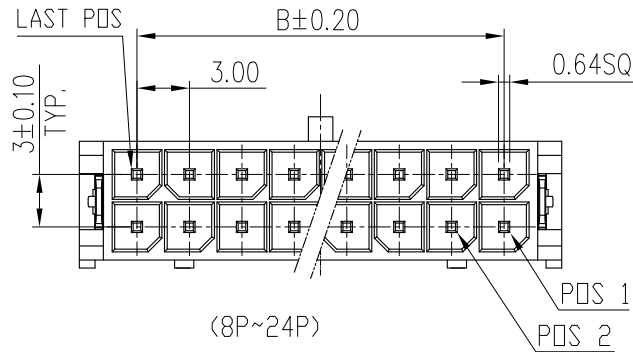
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A	NE-14124	RELEASE FOR RoHS	2014-06-24	Debby Hung
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	2016-09-13	Aqua Chou
C	NE-22173	DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-08-31	Karen Su

NOTE:

- MATERIAL  
INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK  
CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.  
BOARDLOCK: COPPER ALLOY.
- FINISH:  
CONTACT: SELECTIVE PLATING. ;  
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;  
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.  
BOARDLOCK:  
MATTE TIN 100u" MIN. PLATING;  
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- APPLICABLE P.C.BOARD THICKNESS: 1.60mm
- PRODUCT SPECIFICATION REFER TO : PS-7528
- PACKING MUST BE PER AMPHENOL PACKING SPECIFICATION
- TO ENSURE CURRENT RATING CAPABILITY, AMPHENOL HIGH CURRENT PART NUMBERS IN THE CHART ARE RECOMMENDED.  
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



WITHOUT BOARDLOCK



WITH BOARDLOCK

POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

PART NO. G88MPXX1XXXEU  
No. OF CIRCUIT

CONTACT & SOLDERING FINISH  
0:100u" MATTE TIN PLATING (OVERALL)  
1:GOLD FLASH (OVERALL)  
2:15u" GOLD PLATING/100u" MATTE TIN  
3:30u" GOLD PLATING/100u" MATTE TIN

BOARDLOCK OPTION  
K: WITH BOARDLOCK  
M: WITHOUT BOARDLOCK

INSULATOR, / DIM E  
1: LCP(NATURAL), /3.20±0.25  
2: LCP (BLACK), /3.20±0.25  
5: LCP(NATURAL), /2.80<sup>+0.25</sup><sub>-0.00</sub>  
6: LCP (BLACK), /2.80<sup>+0.25</sup><sub>-0.00</sub>

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30 X.X ±0.20 X.XX ±0.10	DRAWN Karen Su	2022-08-31	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)	mm	A3	G88MPXX1XXXEU
	CHECKED Joseph Jiang	2022-08-31				
	APPROVED Roger Tsai	2022-08-31				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD		SCALE NA	SHEET 1 OF 4	DWG No. G88MPXX1XXXEU
UNLESS OTHERWISE SPECIFIED						REV. C

Amphenol<sup>®</sup>  
Amphenol Corporation  
Amphenol Taiwan Corporation

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

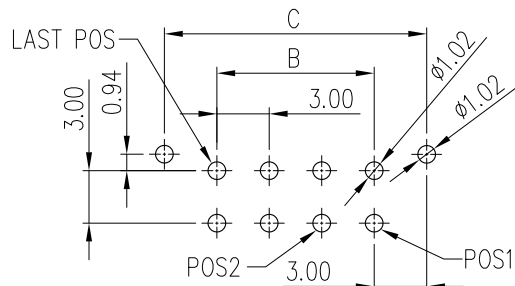
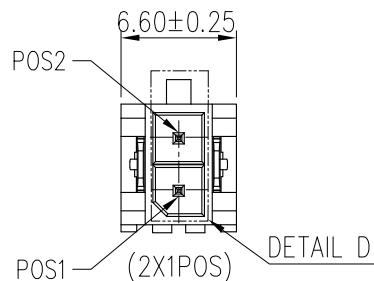
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



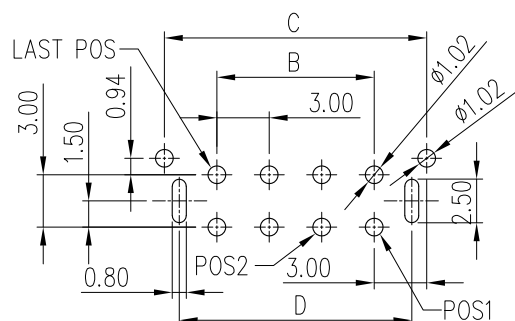
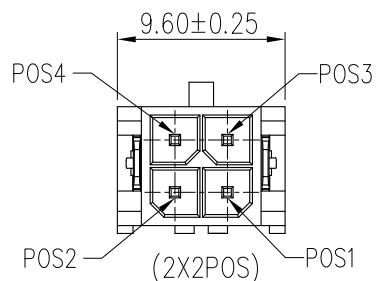
ORIGINAL



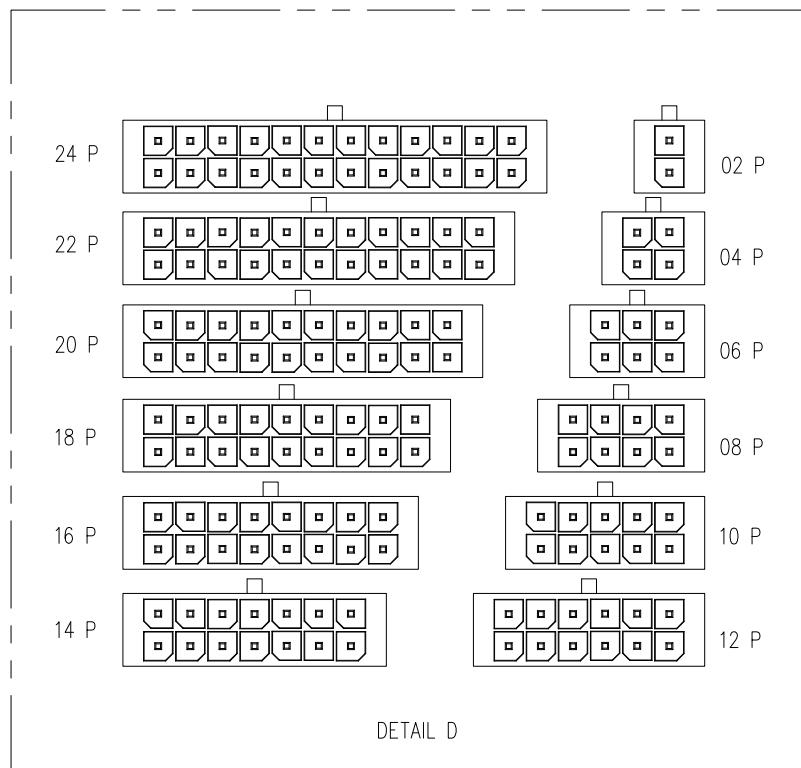
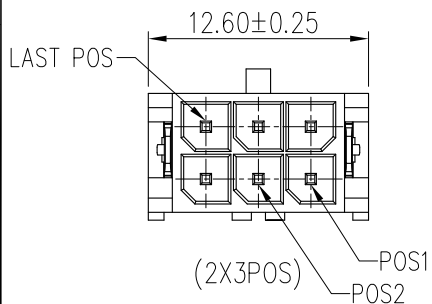
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A	NE-14124	RELEASE FOR RoHS	2014-06-24	Debby Hung
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	2016-09-13	Aqua Chou
C	NE-22173	DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-08-31	Karen Su



2~24P WITHOUT BOARDLOCK  
RECOMMENDED PCB LAYOUT  
(ALL TOLERANCE ±0.05)



2~24P WITH BOARDLOCK  
RECOMMENDED PCB LAYOUT  
(ALL TOLERANCE ±0.05)



TOLERANCE	APPROVALS	DATE	TITLE		Amphenol <sup>®</sup>		
X. ±0.30	DRAWN Karen Su	2022-08-31	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation		
X.X ±0.20	CHECKED Joseph Jiang	2022-08-31					
X.XXX ±0.10	APPROVED Roger Tsai	2022-08-31					
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU		
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 2 OF 4	DWG No. G88MPXX1XXXEU REV. C		

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

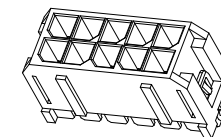


ORIGINAL

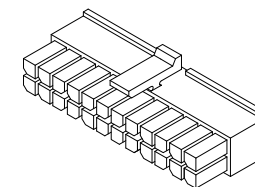


REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A	NE-14124	RELEASE FOR RoHS	2014-06-24	Debby Hung
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	2016-09-13	Aqua Chou
C	NE-22173	DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-08-31	Karen Su

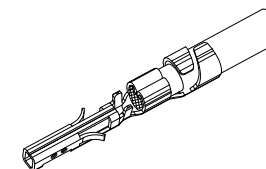
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021XXXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041XXXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061XXXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081XXXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101XXXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121XXXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141XXXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161XXXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181XXXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201XXXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221XXXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241XXXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:  
TO ENSURE CURRENT RATING CAPABILITY,  
AMPHENOL HIGH CURRENT PART NUMBERS IN THE  
CHART ARE RECOMMENDED.  
(G88MPH CABLE HOUSING SERIES WITH G88MPC  
CABLE TERMINAL SERIES)

TOLERANCE		APPROVALS		DATE	TITLE G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)	 Amphenol Corporation Amphenol Taiwan Corporation			
X.		DRAWN	Karen Su	2022-08-31					
X.X	±0.30	CHECKED	Joseph Jiang	2022-08-31					
X.XX	±0.20	APPROVED	Roger Tsai	2022-08-31					
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		CUST DWG	PROJECT CODE PHD		UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU
						SCALE NA	SHEET 3 OF 4	DWG No. G88MPXX1XXXEU	REV. C

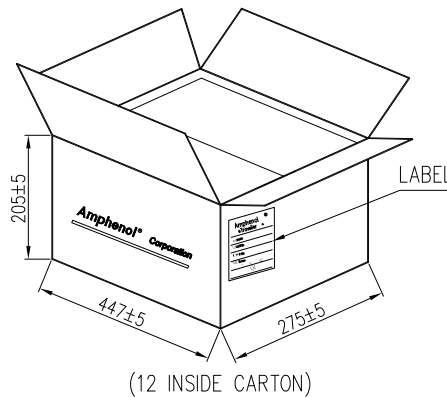
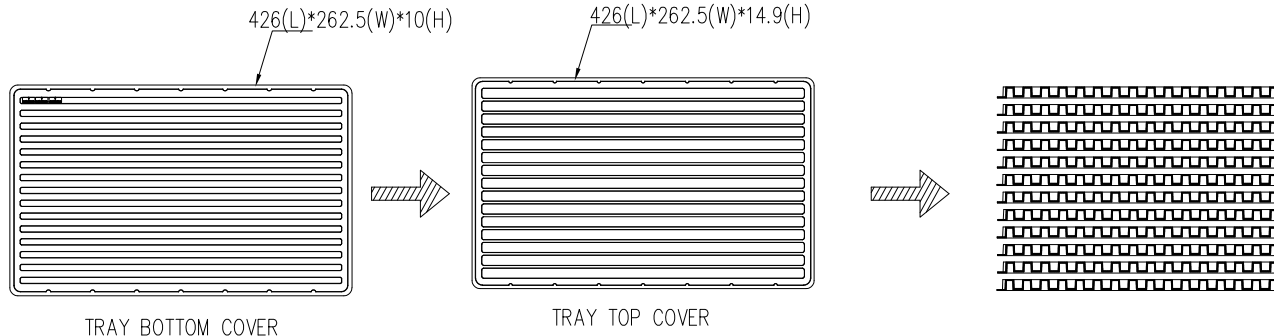
This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.  
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
A	NE-14124	RELEASE FOR RoHS	2014-06-24	Debby Hung
B	NE-16211	ADDED LCP NATURAL/BOARDLOCK/TAIL OPTION	2016-09-13	Aqua Chou
C	NE-22173	DIM3.06 CHANGE TO DIM3.00 (D4) ADDED WITHOUT BOARDLOCK PCB LAYOUT UPDATE PCB LAYOUT TOLERANCE	2022-08-31	Karen Su



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:  
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY  
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.  
3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol <sup>®</sup>	
X. ±0.30	DRAWN Karen Su	2022-08-31	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/KINK BLOCK (TRAY PACKING)		Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Joseph Jiang	2022-08-31				
X.XXX ±0.10	APPROVED Roger Tsai	2022-08-31				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G88MPXX1XXXEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 4 OF 4	DWG No. G88MPXX1XXXEU REV. C	